

Delta Liquid Cooling Solution

tMPBU | FMBG
Oct/2023



【お問い合わせ先】

JEMCO 株式会社ジェムコ

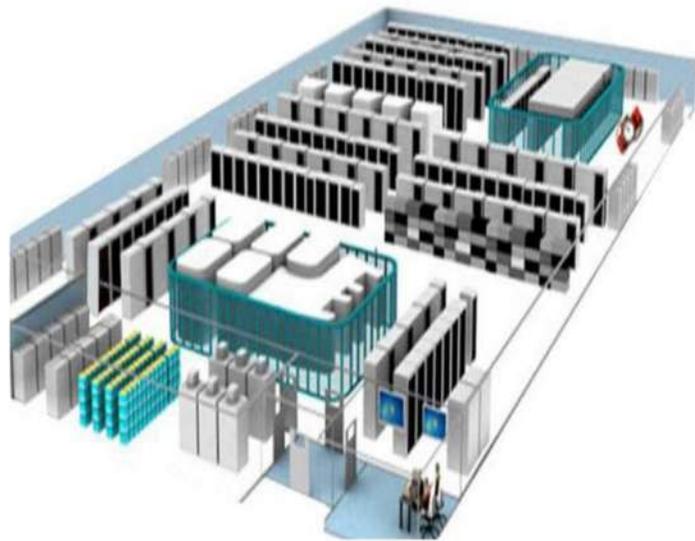
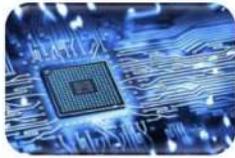
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Delta Liquid Cooling Solution Portfolio

Big Data

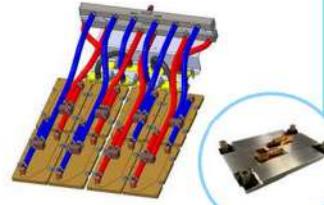
High Performance Computing

AI



Data Center Construction

Server Level



Closed loop (assisted air)
Open loop (assisted air/ facility water)

Rack Level



Liquid to Air CDU
Liquid to Liquid CDU

System level



Manifold
In-row CDU
Immersion Cooling

Feature

- Various high performance standard cold plate for data center liquid cooling
- Optimization for cold plate and loop design
- Integrating Delta DC fan and DC pump



Cold plate

Cold plate loop solution

Feature

- Low power consumption
- Integrating Delta fan and pump
- Redundant pump design



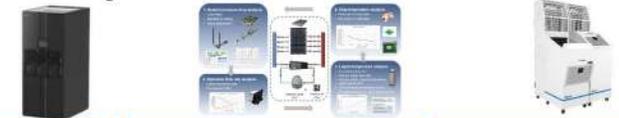
L-A CDU

RPU

L-L CDU

Feature

- High cooling capacity in row CDU
- Standardized, modularized design for immersion cooling solution



In-row CDU

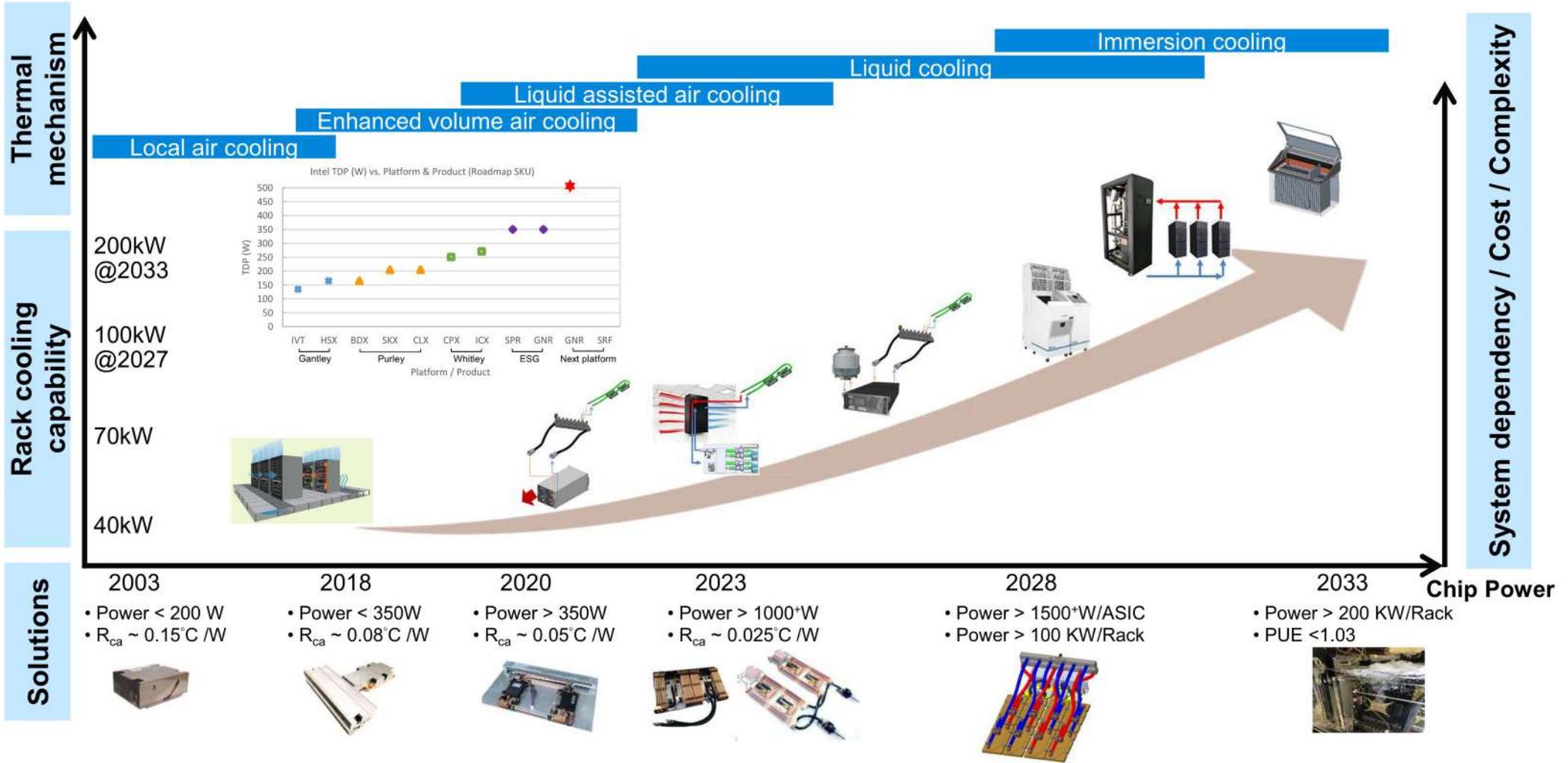
Optimization LCS process

Immersion cooling

RPU: Reservoir pumping unit

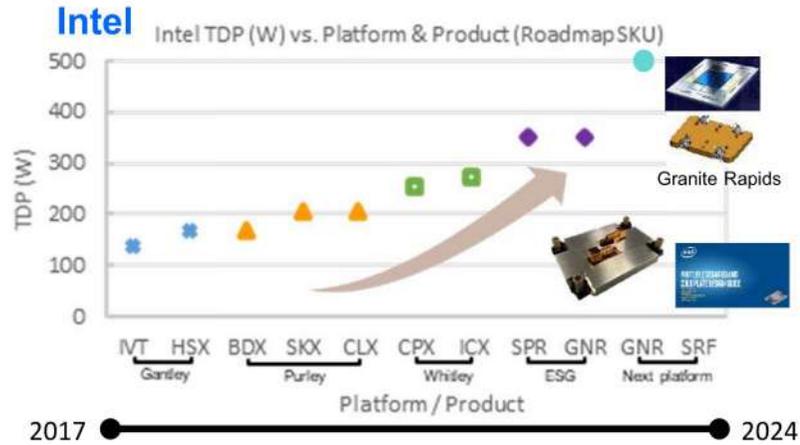


Data Center Thermal Solution Resolution

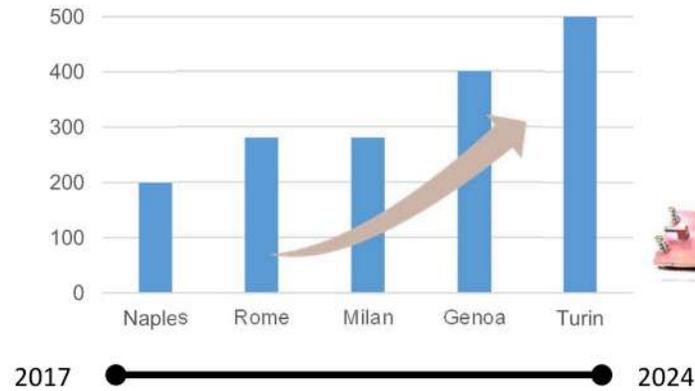


Commodity CPU/GPU vs Delta Cold Plate Solution

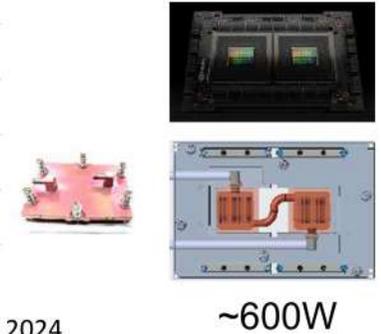
CPU



AMD



nVIDIA – C2



GPU

GPU Model	Approximate TDP (W)
AMD- MI200	~560W
AMD- MI300C	~550W
nVIDIA – SXM4	~500W
nVIDIA – SXM5	~700W
nVIDIA – GH200	~1000W

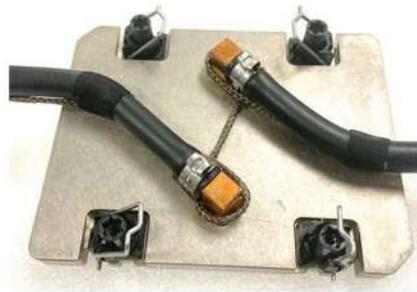


Commodity CPU Cold Plate Performance

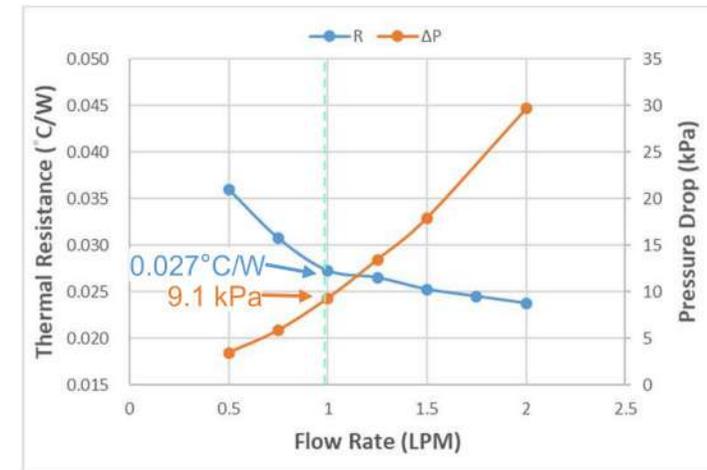
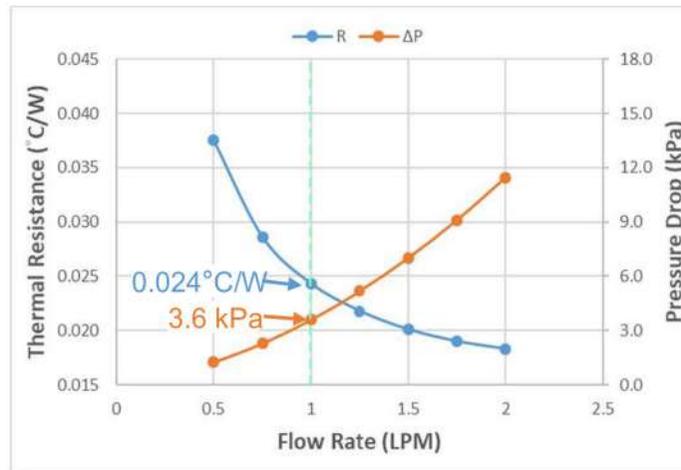
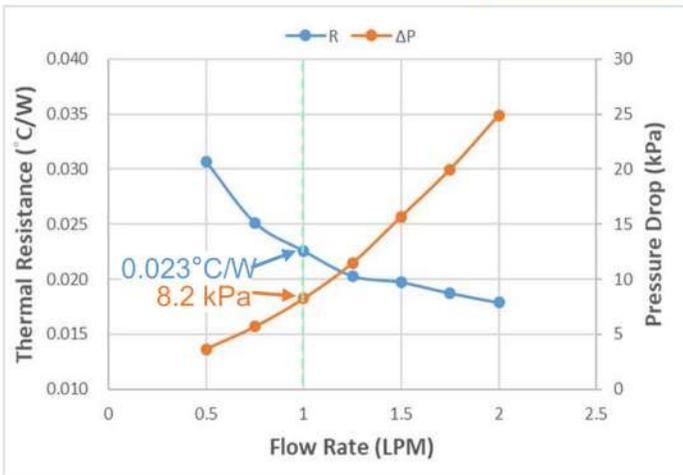
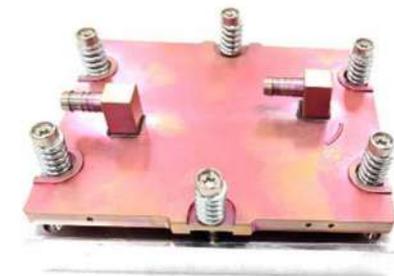
- Model: Intel Sapphire Rapids
- TDP: 350 W
- Stage: MP



- Model: Intel Granite Rapids
- TDP: 500 W
- Stage: 2023/Sep MP



- Model: AMD Genoa
- TDP: 400 W
- Stage: MP



Intel doc#: 602060
 Approved by Intel as LCS ecosystem solution listed in design guideline

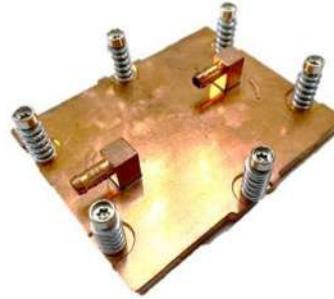


Commodity GPU Cold Plate Performance

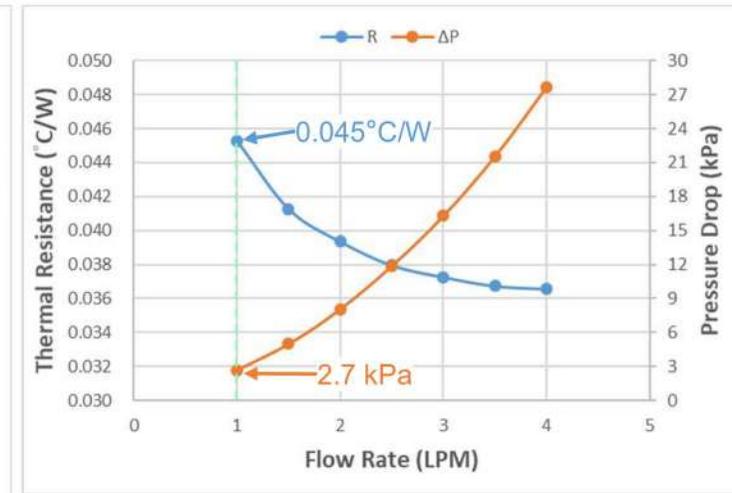
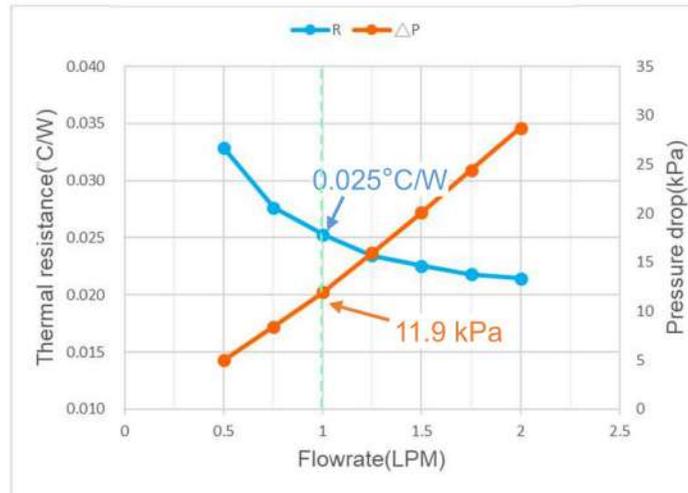
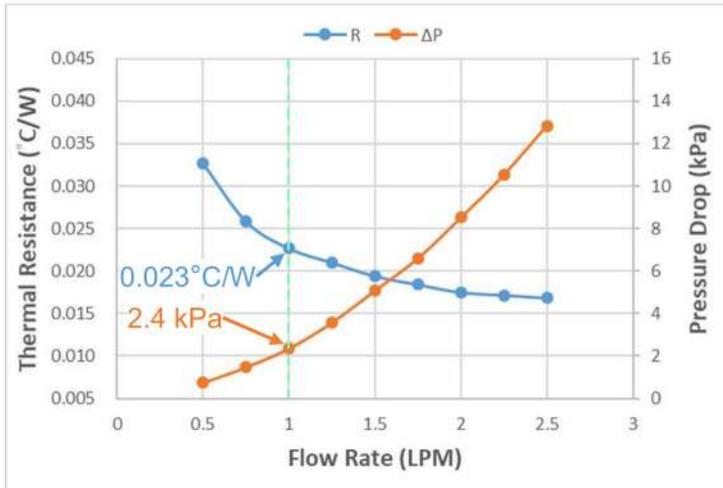
- Model: AMD MI200
- TDP: 560 W
- Stage: MP



- Model: AMD MI300 C
- TDP: 550 W
- Stage: MP

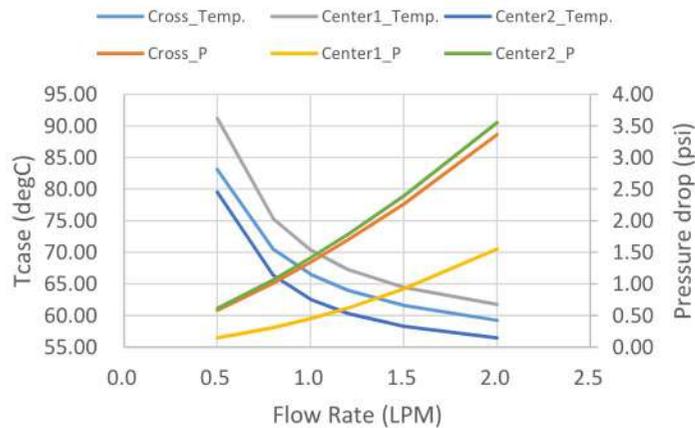
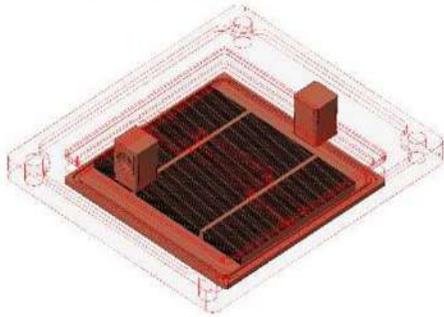


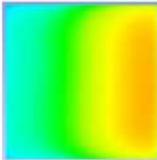
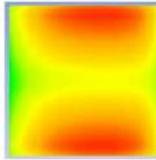
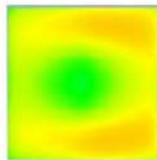
- Model: nVIDIA H100
- TDP: 700 W
- Stage: MP



High TDP Liquid Cooling Technology - 1.5KW ASIC

- Heat source : 70x70 mm
- Power: 1500W
- Coolant : PG25

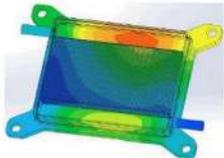
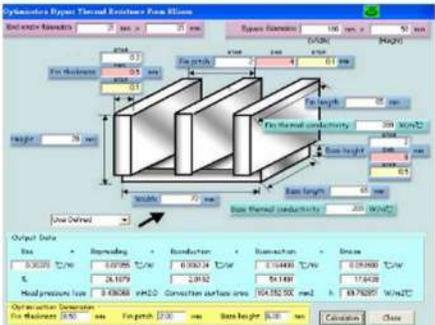


	Version A	Version B	Version C
Flow schematic	Cross flow	Low flow impedance design	Low thermal resistance design
Fin Density (FPI)	84.6	84.6	84.6
Fin Width (mm)	70.0	70.0	70.0
Fin thickness (mm)	0.15	0.15	0.15
Flow rate (LPM)	1.0	1.0	1.0
Thermal Resistance (°C/W)	0.0190	0.0216	0.0164
T _{inlet} (°C)	38.0	38.0	38.0
T _{case} (°C) , center of lid	66.5	70.4	62.6
Pressure drop (psi)	1.34	0.45	1.41
Temperature distribution			

Ready technology for high thermal design power ASIC

Cold Plate Technology

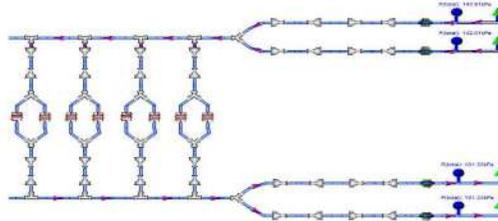
■ Analysis Tool – Self-developed Program/ Simulation Software



ANSYS icepak



FloTHERM®

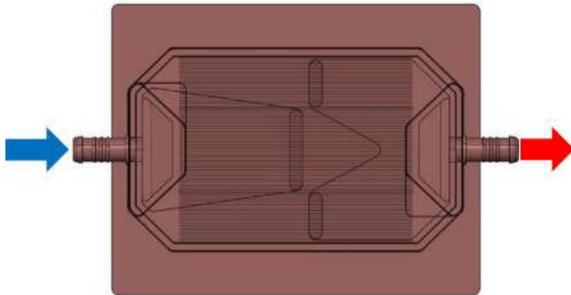


DELTA Self-developed program

■ Cold Plate Design Technology



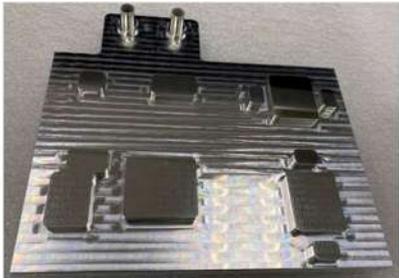
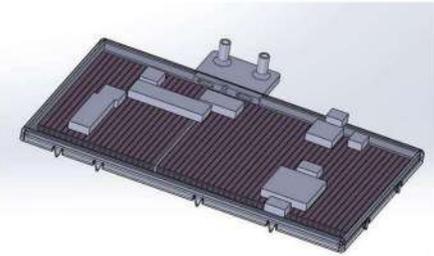
Impingement flow design
 Pressure Impedance 15% ↓



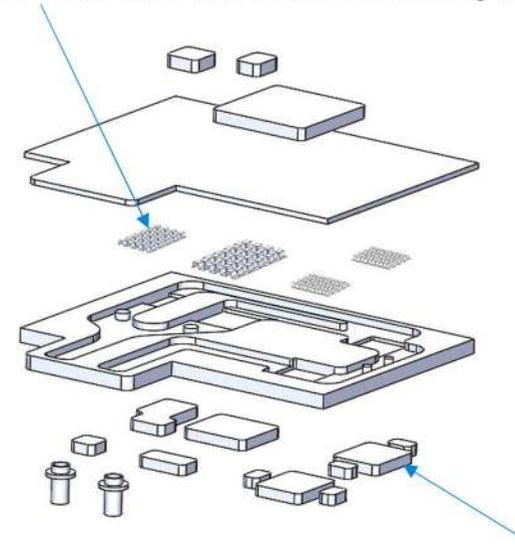
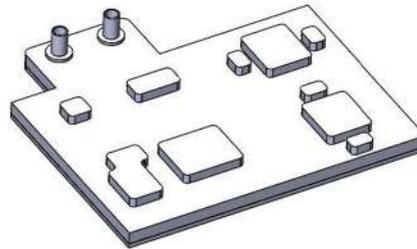
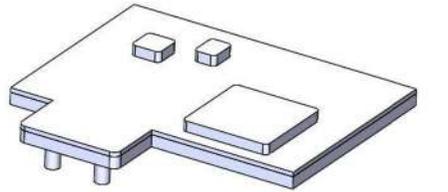
Impingement flow & reflow design
 Performance 10% ↑ with Same Pressure Impedance

AL Brazing Cold Plate

- Inner structure – Stacked fin/Folded fin/Skiving fin can be selected



Brazing coldplate



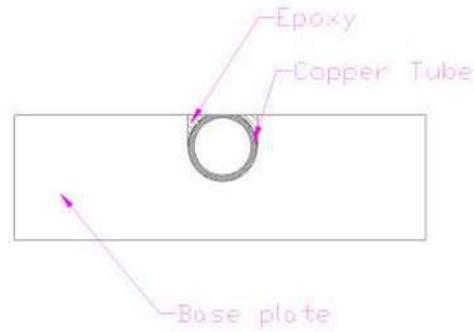
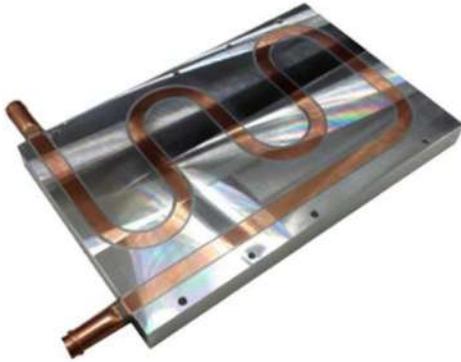
- Multiple heat sources contact



Capacity

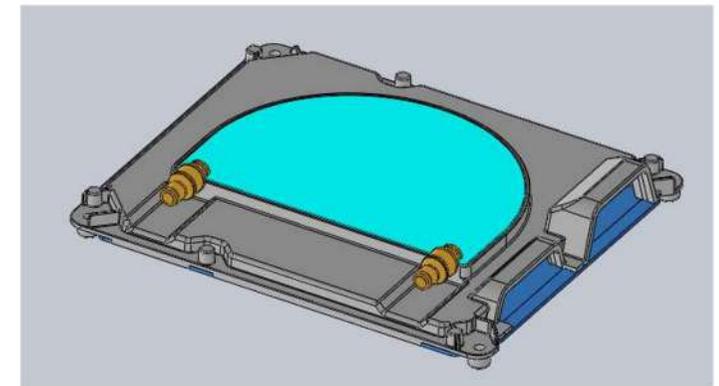
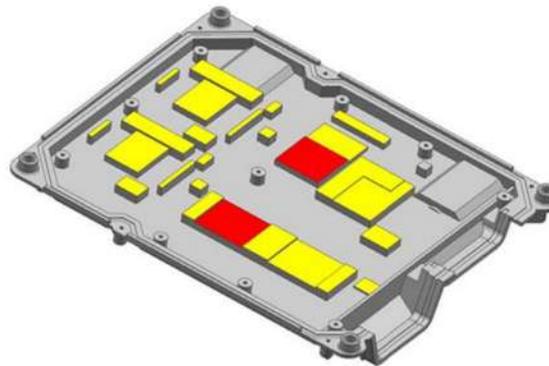
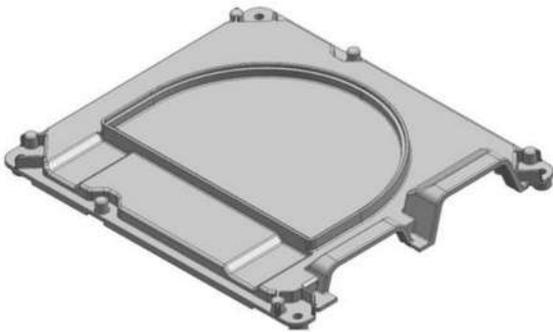
- Composite material
- Brazing material
- Various fin structure:
 - extrusion/stacked fin/skive fin/Folded fin
- Stacked fin:
 - fin thickness: 0.3mm; fin gap: 0.5mm

Tube Embedded Cold Plate



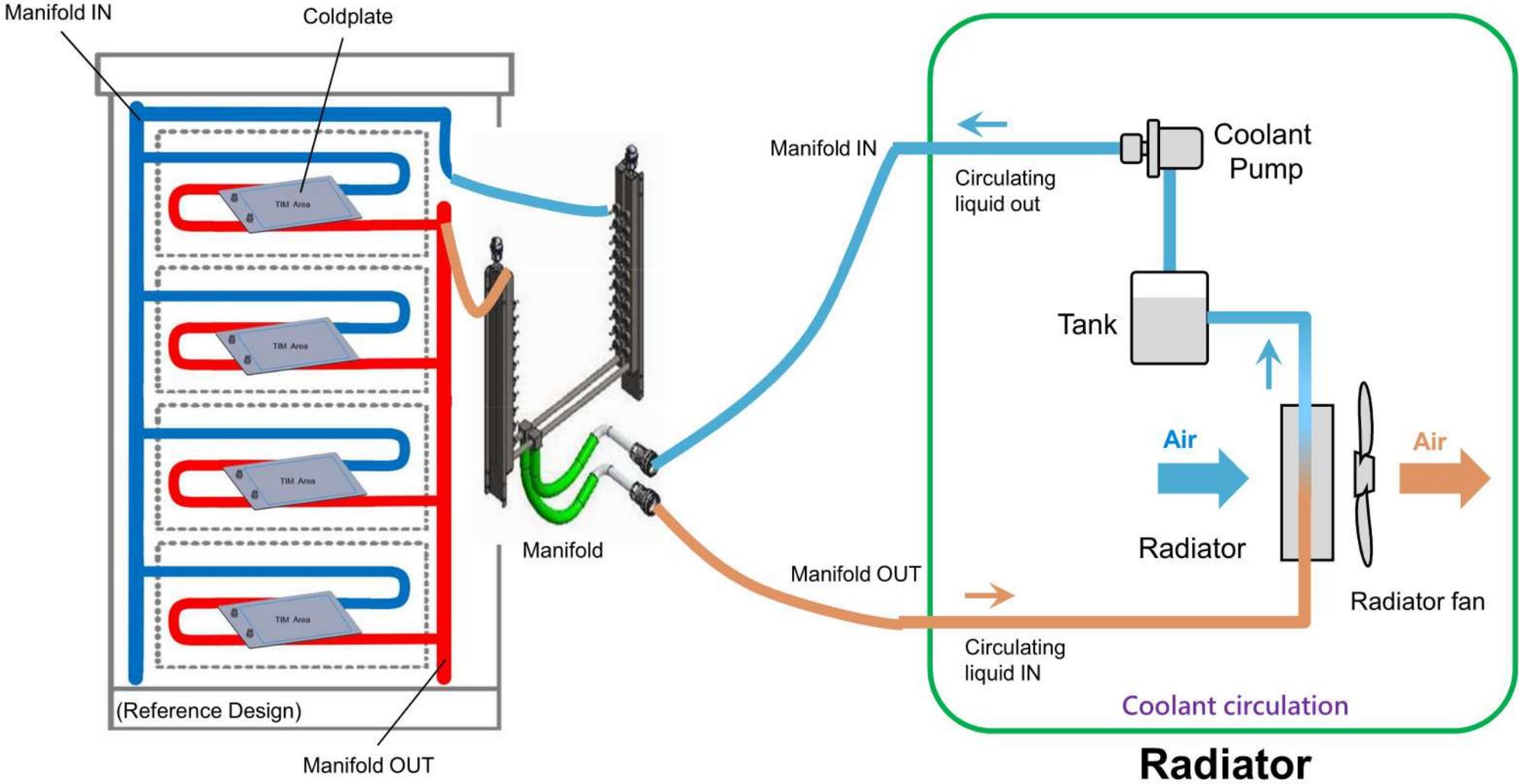
Capacity

- Al/Cu base
- C12200 tube material
- High thermal conductivity epoxy
- Tube exposed



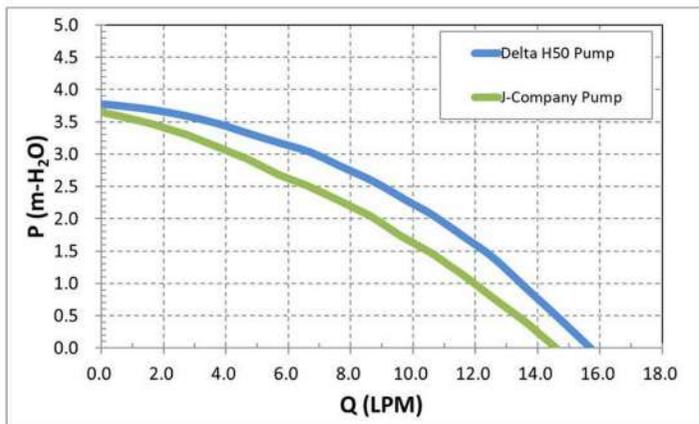
- By using copper tube embedded in **die casting** to handle the heat for control unit

Radiator option proposal

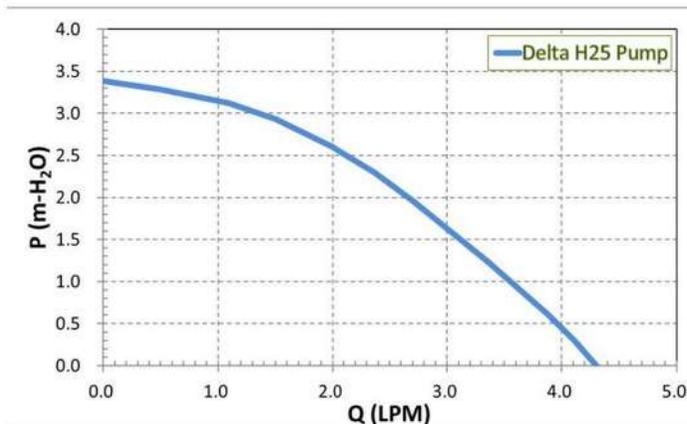
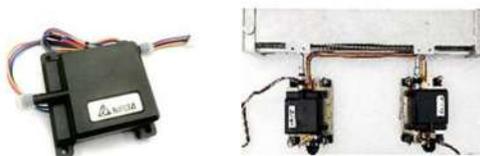


Delta Pump Performance

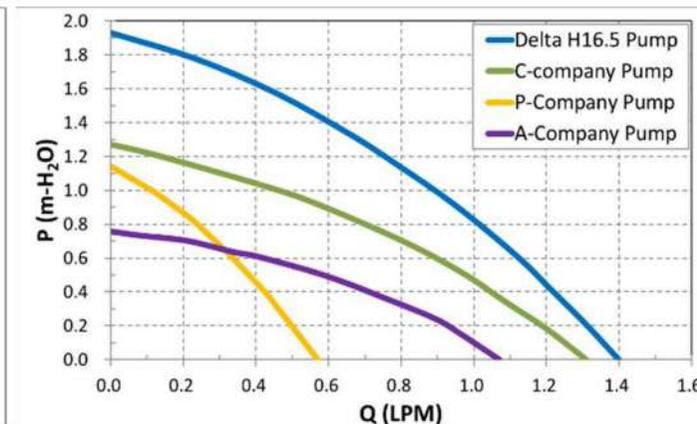
2U Application (H50mm)



1.5U Application (H25mm)



1U Application (H16.5mm)



Verified MTTF 50 °C (hrs)	2,077,723
Verified L ₁₀ 50 °C (hrs)	296,818

Verified MTTF 50 °C (hrs)	532,407 (Processing)
Verified L ₁₀ 50 °C (hrs)	76,058 (Processing)

Verified MTTF 50 °C (hrs)	775,632
Verified L ₁₀ 50 °C (hrs)	110,805

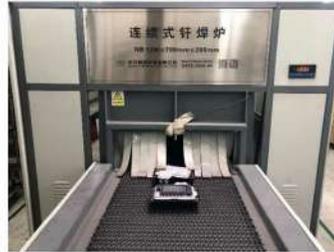
With self-developed technology
Delta pump features both high PQ performance with long life expectancy

Liquid Cooling Solution Manufacturing Capability

■ Brazing oven - Copper



■ Brazing oven - Aluminum



■ Brazing material dispenser



■ Welding



■ Flow & Thermal Testing



■ Cleaning



■ Drying



■ Vacuum Oven



■ Helium Testing



■ Run In & Burn In Chamber



■ Pressure Holding Test



■ Pressure Pulse / Decay Test



■ Reliability : Burst Test



In-line process/testing and inspection for quality control

Coolant Distribution Unit

Liquid to Liquid CDU

Model:DHS-X430175-01



- 4U height
- 450 (W) x 900 (D) x 175 (H) mm
- Cooling capacity: 100 kW @ $T_{\text{approach}}=18^{\circ}\text{C}$
- Full load power consumption: 580 W
- Modbus / Redfish / Webserver
- Smart self-protection & High performance pump
- Facility chiller
- Comply UL 62368



Intel doc#: 636703
 Approved by Intel as LCS ecosystem solution
 listed in design guideline

Liquid to Air CDU

Model:FHS-X440350-01



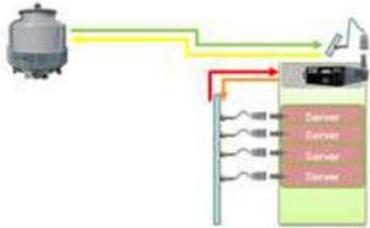
- 8U height
- 450 (W) x 900 (D) x 350 (H) mm
- Cooling capacity: 14 kW @ $T_{\text{approach}}=25^{\circ}\text{C}$
- Full load power consumption: 2,200 W
- Modbus / Redfish / Webserver
- Smart self-protection &
- High performance pump & fan
- CDU cooling fan
- Comply UL60335



Approved by Intel as liquid cooling solution ecosystem listed in design guideline

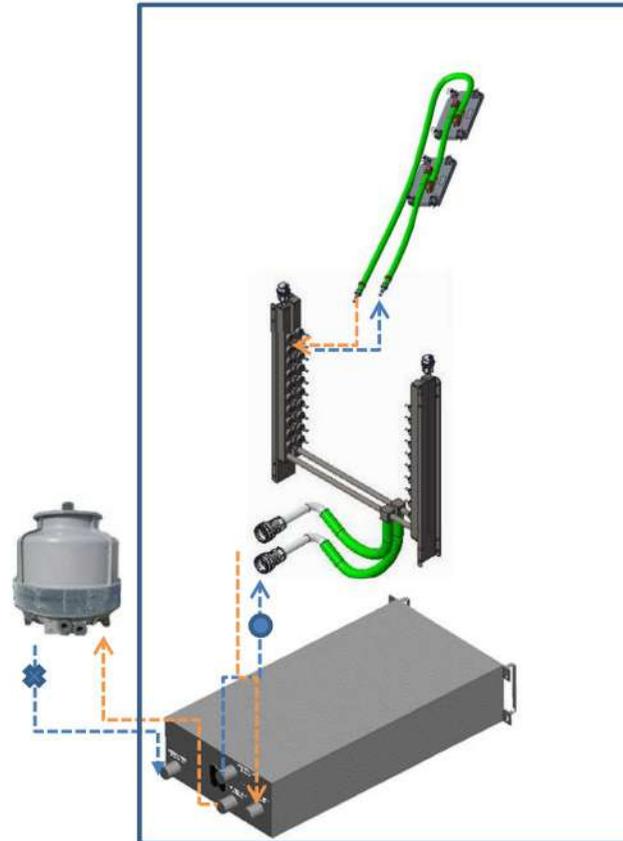
Coolant Distribution Unit – Liquid to Liquid

Liquid to Liquid CDU



Liquid to liquid CDU (4U height)

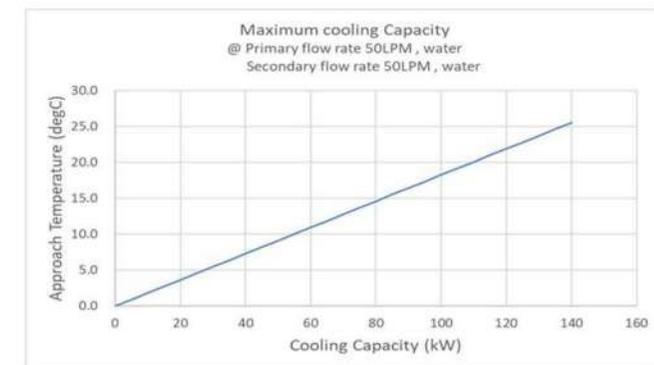
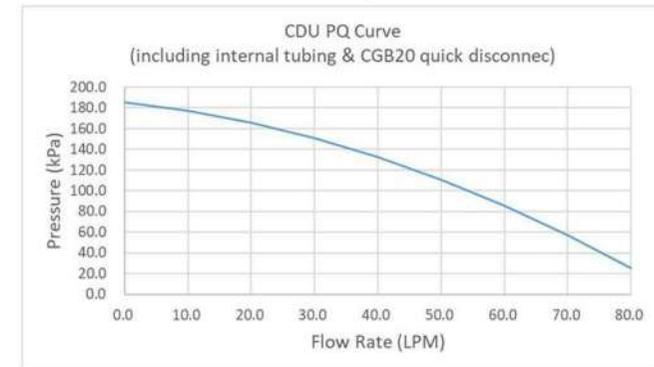
- **Need facility chiller**
- 450 (W) x 900 (D) x 175 (H) mm
- Cooling capacity is 100 kW @ approach temperature = 18°C
- Pressure control/
Dew point temperature control/
Liquid flow control/
- Redundant pump design
- Leakage and condensation alarm
- Power consumption: 580 W
- Low power consumption



T app (Approach temperature)
= Secondary supply (●) – Primary supply (✱)

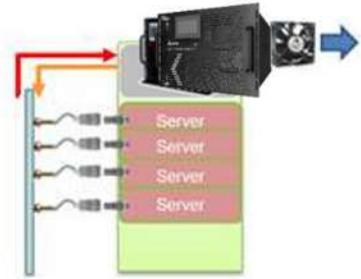


PQ Curve of CDU



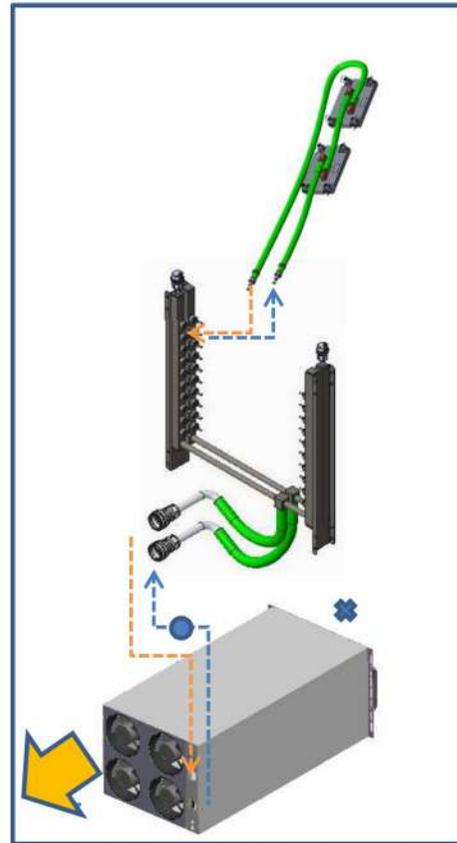
Coolant Distribution Unit – Liquid to Air

Liquid to Air CDU

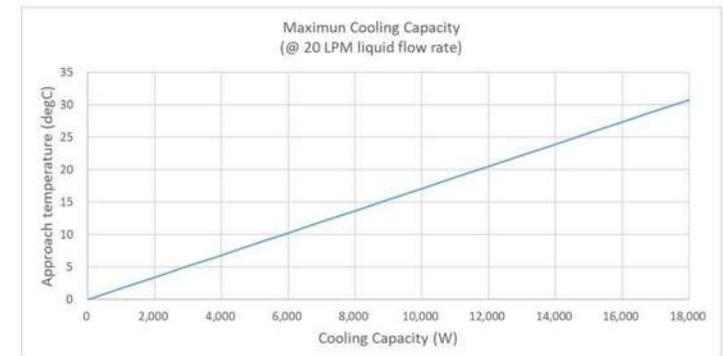
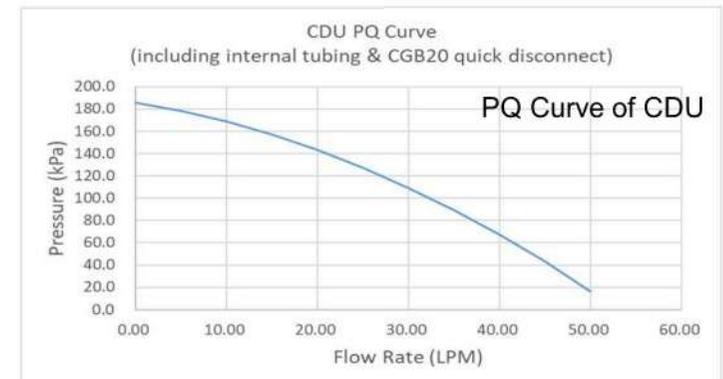


Liquid to Air CDU (8U height)

- **No need facility chiller, easy to build up liquid cooling solution**
- 450 (W) x 900 (D) x 350 (H) mm
- Cooling capacity is 14 kW @ approach temperature = 25°C
- Pressure control/
Liquid flow control/
liquid-air heat exchange
- Redundant pump design
- Leakage alarm
- Power consumption: 2,000 W



T_{app} (Approach temperature)
= Secondary supply (●) – Primary supply (✱)

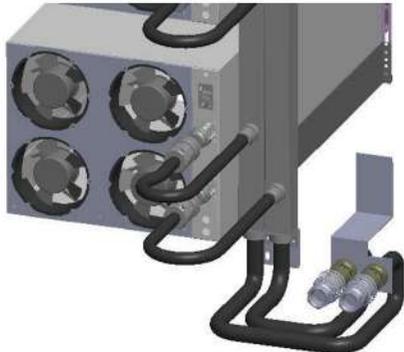
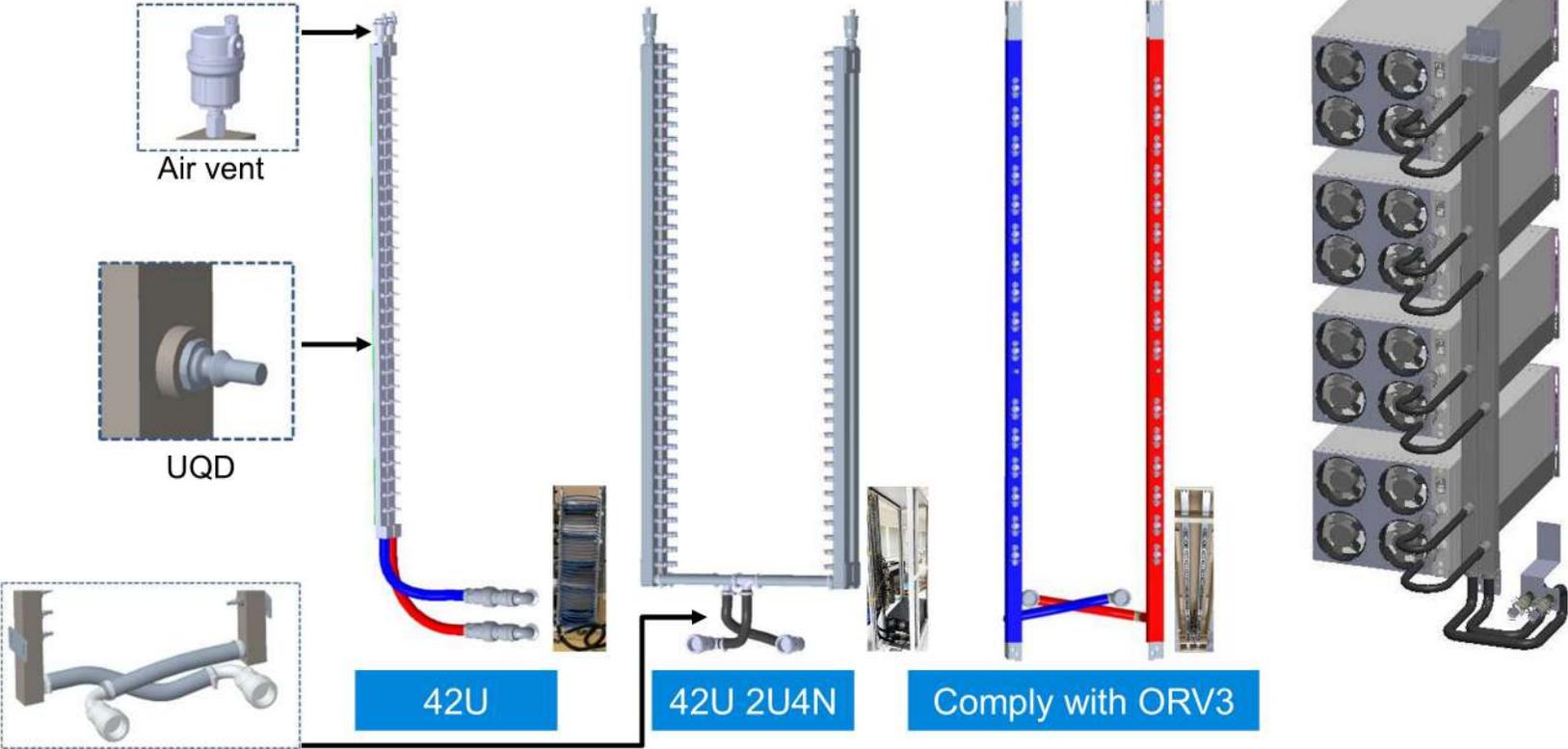


Manifold Design Capability

Manifold design

- Customized per demand
- QD selection
- Highly reliable
- Easy to use
- Materials compatibility

- Hose consideration
- Fluid compatibility
- Wetted material consideration



Manifold Design Capability

Even Distribution

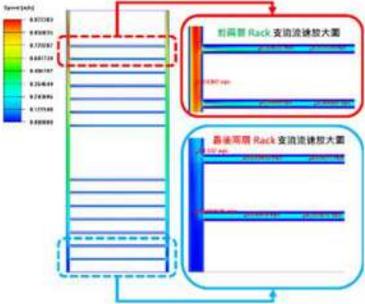
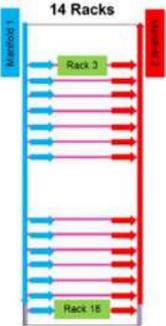
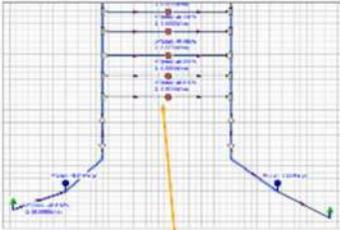
Manifold Distribution Analysis

Manifold
• Total 58 nodes (58 cold plate loops)

Cold plate 58
(node 58)

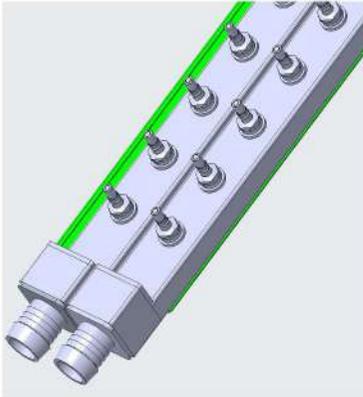


Cold plate 1
(node 1)

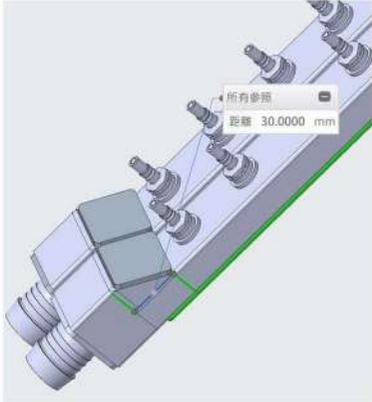
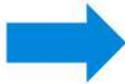


Rack 1 (LPM)	Empty
Rack 2 (LPM)	Empty
Rack 3 (LPM)	1.630
Rack 4 (LPM)	1.626
Rack 5 (LPM)	1.618
Rack 6 (LPM)	1.611
Rack 7 (LPM)	1.605
Rack 8 (LPM)	1.600
Rack 9 (LPM)	1.596
Rack 10 (LPM)	Empty
Rack 11 (LPM)	Empty
Rack 12 (LPM)	1.586
Rack 13 (LPM)	1.584
Rack 14 (LPM)	1.582
Rack 15 (LPM)	1.580
Rack 16 (LPM)	1.579
Rack 17 (LPM)	1.579
Rack 18 (LPM)	1.579
Average \bar{x} (LPM)	1.597
standard deviation σ (LPM)	0.018
ΔP_{total} (Pa)	12832.5
Total Flow Rate (LPM)	22.4
Flow Uniformity ($\sigma/\bar{x} \times 100\%$)	1.109 %

Low Pressure Drop



Improve
pressure drop



Customized per Demand

Front view Side view



Air vent



QD: SCG03



Barb

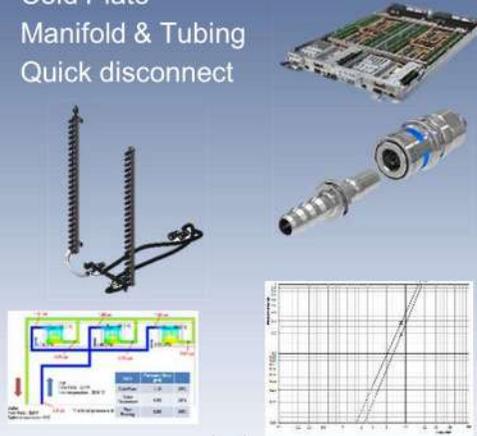


Fix feature to
PDU rail

Integration Capability for Total Liquid Cooling Solution

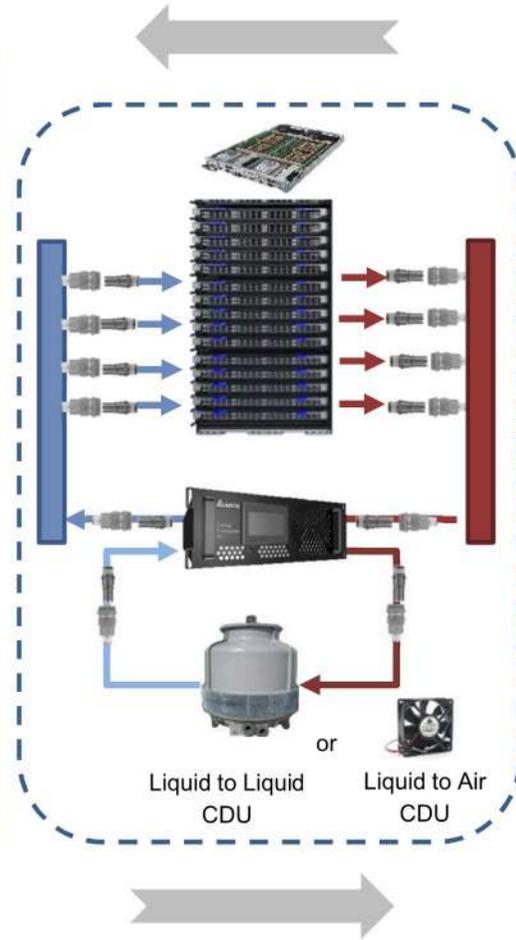
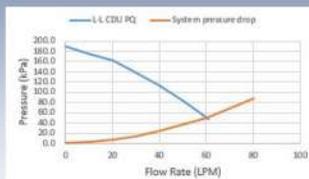
1. System pressure drop analysis

- Cold Plate
- Manifold & Tubing
- Quick disconnect



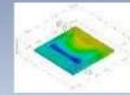
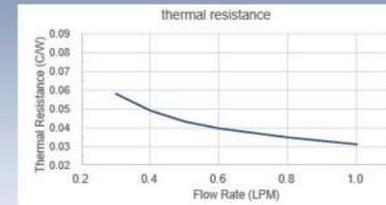
2. Operation flow rate analysis

- System pressure drop
- PQ curve of CDU



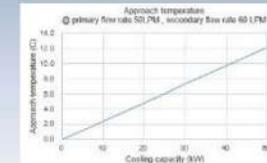
4. Chip temperature analysis

- Flow rate of cold plate
- RQ curve of cold plate



3. Liquid temperature analysis

- Secondary flow rate
- Primary water flow rate
- Primary water supply temperature
- Heat load of rack
- CDU thermal performance curve (Cooling capacity vs. app. temperature)



Facility water assumption: (Primary side)	
Primary flow rate (LPM)	50.0
Primary supply temperature (°C)	32.0
Secondary side output :	
Total Heat load (kW)	30.0
Secondary flow rate (LPM)	59.9
Secondary supply temperature (°C)	28.3
Secondary return temperature (°C)	28.9

CDU Manufacturing Capability

CDU Production Line



Intelligent Visual Image Detection



Smart screwdriving system



Function Test

Equipment Coolant: Dow PG25%
 Equipment Filter mesh:25um
 Equipment PH Monitor: 8.0~10.5

报警: OK
 故障: OK

Burn-in Test

Equipment Coolant: Dow PG25%
 Equipment Filter mesh:25um
 Equipment PH Monitor:8.0~10.5

报警: OK
 故障: OK

Drying & Filling

Filling with Nitrogen